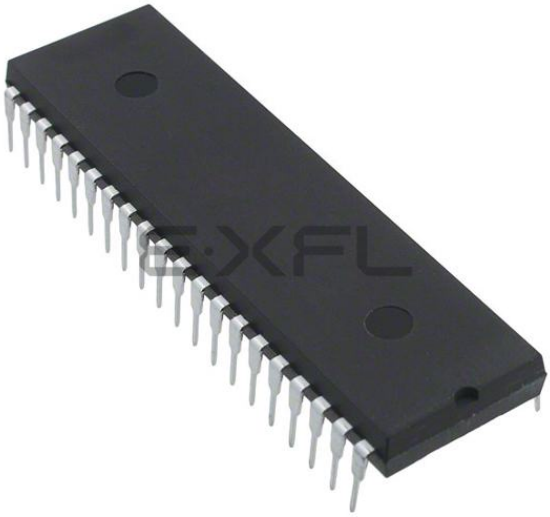

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	3KB (2K x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	134 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f59-e-p

NOTES:

NOTES:

3.4 Option Register

The Option register is a 6-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W register will be transferred to the Option register. A Reset sets the Option<5:0> bits.

REGISTER 3-2: OPTION REGISTER

U-0	U-0	W-1	W-1	W-1	W-1	W-1	W-1
—	—	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7-6 **Unimplemented**: Read as '0'

bit 5 **T0CS**: Timer0 Clock Source Select bit
1 = Transition on T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on T0CKI pin
0 = Increment on low-to-high transition on T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler assigned to the WDT
0 = Prescaler assigned to Timer0

bit 2-0 **PS<2:0>**: Prescaler rate select bits

Bit Value	Timer0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

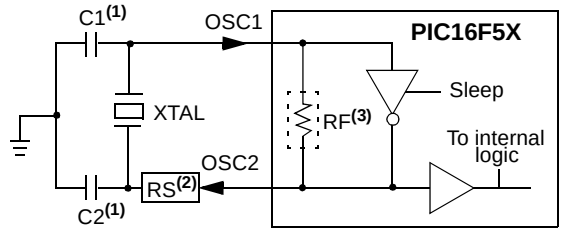
The PIC16F5X devices can be operated in four different oscillator modes. The user can program two Configuration bits (FOSC1:FOSC0) to select one of these four modes:

- LP: Low-power Crystal
- XT: Crystal/Resonator
- HS: High-speed Crystal/Resonator
- RC: Resistor/Capacitor

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16F5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.
2: A series resistor (RS) may be required.
3: RF varies with the Oscillator mode chosen (approx. value = 10 MΩ).

FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

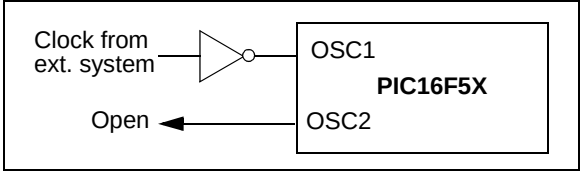


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Osc Type	Resonator Freq.	Cap. Range C1	Cap. Range C2
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-33 pF 10-22 pF	68-100 pF 15-33 pF 10-22 pF
HS	8.0 MHz 16.0 MHz	10-22 pF 10 pF	10-22 pF 10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq.	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz 200 kHz 455 kHz 1 MHz 2 MHz 4 MHz	15-30 pF 15-30 pF 15-30 pF 15-30 pF 15 pF 15 pF	200-300 pF 100-200 pF 15-100 pF 15-30 pF 15 pF 15 pF
HS	4 MHz 8 MHz 20 MHz	15 pF 15 pF 15 pF	15 pF 15 pF 15 pF

Note 1: For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specifications. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note 1: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.

2: The user should verify that the device oscillator starts and performs as expected. Adjusting the loading capacitor values and/or the Oscillator mode may be required.

TABLE 5-3: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-on Reset	$\overline{\text{MCLR}}$ or WDT Reset
W	N/A	xxxx xxxx	uuuu uuuu
TRIS	N/A	1111 1111	1111 1111
OPTION	N/A	--11 1111	--11 1111
INDF	00h	xxxx xxxx	uuuu uuuu
TMR0	01h	xxxx xxxx	uuuu uuuu
PCL	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	000q quuu
FSR(1)	04h	111x xxxx	111u uuuu
FSR(2)	04h	1xxx xxxx	1uuu uuuu
FSR(3)	04h	xxxx xxxx	uuuu uuuu
PORTA	05h	---- xxxx	---- uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu
PORTC(4)	07h	xxxx xxxx	uuuu uuuu
PORTD(5)	08h	xxxx xxxx	uuuu uuuu
PORTE(5)	09h	xxxx ----	uuuu ----

Legend: u = unchanged, x = unknown, – = unimplemented, read as '0', q = see tables in Table 5-1 for possible values.

Note 1: PIC16F54 only.

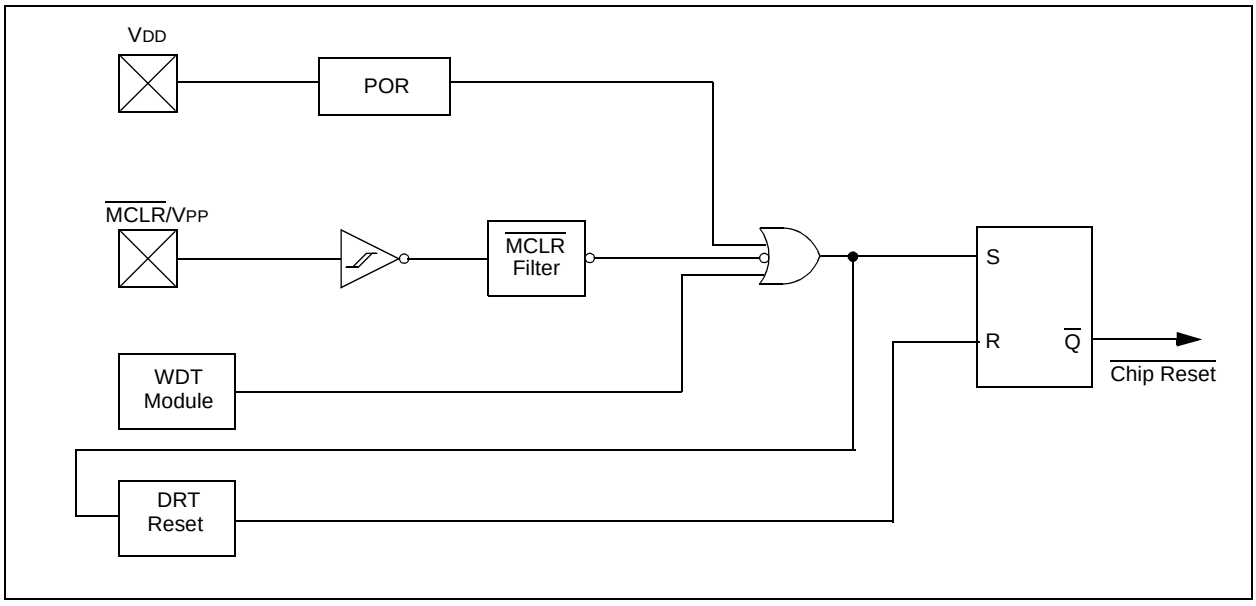
2: PIC16F57 only.

3: PIC16F59 only.

4: General purpose register file on PIC16F54.

5: General purpose register file on PIC16F54 and PIC16F57.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



NOTES:

BSF **Bit Set f**

Syntax: [*label*] BSF f, b

Operands: 0 ≤ f ≤ 31
0 ≤ b ≤ 7

Operation: 1 → (f<b>)

Status Affected: None

Encoding:

0101	bbbf	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example:
```
BSF    FLAG_REG,   7
```
Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test f, Skip if Clear**

Syntax: [*label*] BTFSC f, b

Operands: 0 ≤ f ≤ 31
0 ≤ b ≤ 7

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

0110	bbbf	ffff

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped.
If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE   BTFSC  FLAG,1
FALSE  GOTO   PROCESS_CODE
TRUE   •
       •
       •
```
Before Instruction
PC = address (HERE)
After Instruction
if FLAG<1> = 0,
PC = address (TRUE);
if FLAG<1> = 1,
PC = address (FALSE)

BTFSS **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f, b

Operands: 0 ≤ f ≤ 31
0 ≤ b < 7

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

0111	bbbf	ffff

Description: If bit 'b' in register 'f' is '1', then the next instruction is skipped.
If bit 'b' is '1', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE   BTFSS  FLAG,1
FALSE  GOTO   PROCESS_CODE
TRUE   •
       •
       •
```
Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0,
PC = address (FALSE);
if FLAG<1> = 1,
PC = address (TRUE)

CALL **Subroutine Call**

Syntax: [*label*] CALL k

Operands: $0 \le k \le 255$

Operation: (PC) + 1→ TOS;
k → PC<7:0>;
(Status<6:5>) → PC<10:9>;
0 → PC<8>

Status Affected: None

Encoding:

1001	kkkk	kkkk

Description: Subroutine call. First, return address (PC + 1) is pushed onto the stack. The eight-bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. CALL is a two-cycle instruction.

Words: 1

Cycles: 2

Example:
```
HERE    CALL    THERE
```
Before Instruction
PC = address (HERE)
After Instruction
PC = address (THERE)
TOS = address (HERE + 1)

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 31$

Operation: 00h → (f);
1 → Z

Status Affected: Z

Encoding:

0000	011f	ffff

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Example:
```
CLRF    FLAG_REG
```
Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W);
1 → Z

Status Affected: Z

Encoding:

0000	0100	0000

Description: The W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example:
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler (if assigned);
1 → $\overline{TO}$;
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0100

Description: The CLRWDT instruction resets the WDT. It also resets the prescaler if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example:
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: $(\bar{f}) \rightarrow (dest)$

Status Affected: Z

Encoding:

0010	01df	ffff

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example:
```
COMF   REG1,0
```
Before Instruction
REG1 = 0x13
After Instruction
REG1 = 0x13
W = 0xEC

DECF **Decrement f**

Syntax: [*label*] DECF f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) – 1 → (dest)

Status Affected: Z

Encoding:

0000	11df	ffff

Description: Decrement register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example:
```
DECF    CNT, 1
```
Before Instruction
CNT = 0x01
Z = 0
After Instruction
CNT = 0x00
Z = 1

DECFSZ **Decrement f, Skip if 0**

Syntax: [*label*] DECFSZ f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f) – 1 → d; skip if result = 0

Status Affected: None

Encoding:

0010	11df	ffff

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1'. the result is placed back in register 'f'. If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE     DECFSZ   CNT, 1
         GOTO     LOOP
CONTINUE •
         •
         •
```
Before Instruction
PC = address(HERE)
After Instruction
CNT = CNT - 1;
if CNT = 0,
PC = address (CONTINUE);
if CNT ≠ 0,
PC = address (HERE+1)

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 31$

Operation: (W) → (f)

Status Affected: None

Encoding:

0000	001f	ffff

Description: Move data from the W register to register 'f'.

Words: 1

Cycles: 1

Example:

```
MOVWF  TEMP_REG
```

Before Instruction
TEMP_REG = 0xFF
W = 0x4F
After Instruction
TEMP_REG = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

0000	0000	0000

Description: No operation.

Words: 1

Cycles: 1

Example:

```
NOP
```

OPTION **Load OPTION Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

0000	0000	0010

Description: The content of the W register is loaded into the Option register.

Words: 1

Cycles: 1

Example:

```
OPTION
```

Before Instruction
W = 0x07
After Instruction
OPTION = 0x07

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: $0 \le k \le 255$

Operation: k → (W);
TOS → PC

Status Affected: None

Encoding:

1000	kkkk	kkkk

Description: The W register is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

Words: 1

Cycles: 2

Example:

```
      CALL TABLE;W contains
                ;table offset
                ;value.
      •         ;W now has table
      •         ;value.
TABLE •
      ADDWF PC  ;W = offset
      RETLW k1  ;Begin table
      RETLW k2  ;
      •
      •
      •
      RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

XORLW **Exclusive OR literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

1111	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:

```
XORLW  0xAF
```

Before Instruction
W = 0xB5
After Instruction
W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f, d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

0001	10df	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example:

```
XORWF  REG,1
```

Before Instruction
REG = 0xAF
W = 0xB5
After Instruction
REG = 0x1A
W = 0xB5

11.0 ELECTRICAL SPECIFICATIONS FOR PIC16F54/57

Absolute Maximum Ratings(†)

Ambient Temperature under bias ..... -40°C to +125°C

Storage Temperature ..... -65°C to +150°C

Voltage on V_{DD} with respect to V_{SS} ..... 0V to +6.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS}(1) ..... 0V to +13.5V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to (V_{DD} + 0.6V)

Total power dissipation(2) ..... 800 mW

Max. current out of V_{SS} pin ..... 150 mA

Max. current into V_{DD} pin ..... 100 mA

Max. current into an input pin (T0CKI only) ..... ±500 µA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Max. output current sunk by any I/O pin ..... 25 mA

Max. output current sourced by any I/O pin ..... 25 mA

Max. output current sourced by a single I/O port (PORTA, B or C) ..... 50 mA

Max. output current sunk by a single I/O port (PORTA, B or C) ..... 50 mA

Note 1: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50 to 100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

2: Power Dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

†NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

11.2 DC Characteristics: PIC16F5X (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym.**	**Characteristic/Device**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D010	IDD	**Supply Current(2)**					
			— — — —	170 0.4 1.7 15	450 2.0 7.0 40	µA mA mA µA	FOSC = 4 MHz, VDD = 2.0V, XT or RC mode(3) FOSC = 10 MHz, VDD = 3.0V, HS mode FOSC = 20 MHz, VDD = 5.0V, HS mode FOSC = 32 kHz, VDD = 2.0V, LP mode, WDT disabled
D020	IPD	**Power-down Current(2)**					
			— —	1.0 0.5	15.0 8.0	µA µA	VDD = 2.0V, WDT enabled VDD = 2.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

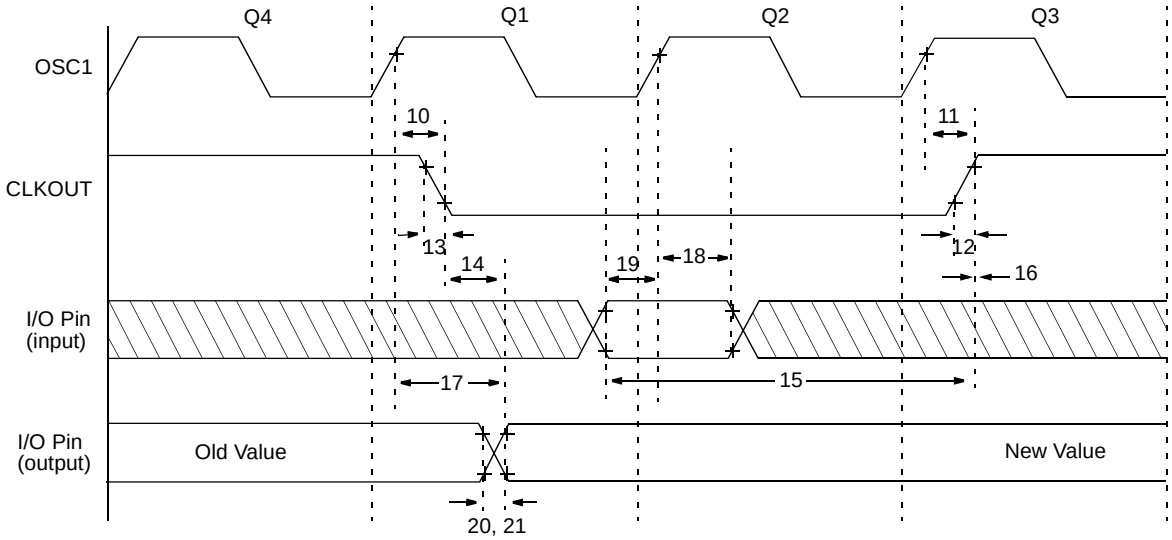
2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature, also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode. The Power-down Current in Sleep mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 11-4: CLKOUT AND I/O TIMING – PIC16F5X



Note: Please refer to Figure 11-2 for load conditions.

TABLE 11-2: CLKOUT AND I/O TIMING REQUIREMENTS – PIC16F5X

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ **(1)**	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ **(1)**	—	15	30**	ns
12	TckR	CLKOUT rise time **(1)**	—	5.0	15**	ns
13	TckF	CLKOUT fall time **(1)**	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid **(1)**	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ **(1)**	0.25 Tcy+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ **(1)**	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid **(2)**	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time **(2, 3)**	—	10	25**	ns
20	TioR	Port output rise time **(2, 4)**	—	10	50**	ns
21	TioF	Port output fall time **(2, 3)**	—	10	25**	ns
21	TioF	Port output fall time **(2, 4)**	—	10	50**	ns

Legend: TBD = To Be Determined.

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 11-2 for load conditions.

3: PIC16F54/57 only.

4: PIC16F59 only.

Package Marking Information (Continued)

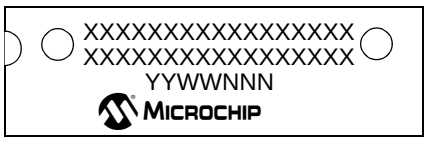
28-Lead SOIC

Example

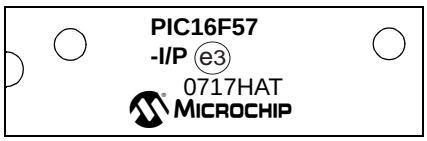
28-Lead SSOP

Example

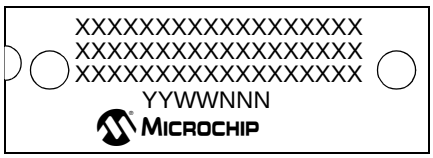
28-Lead SPDIP (.300")

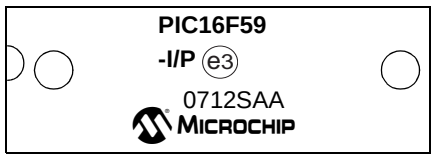


Example

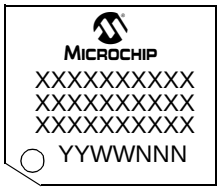


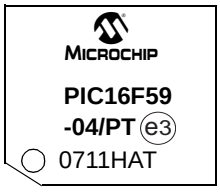
40-Lead PDIP (.600")





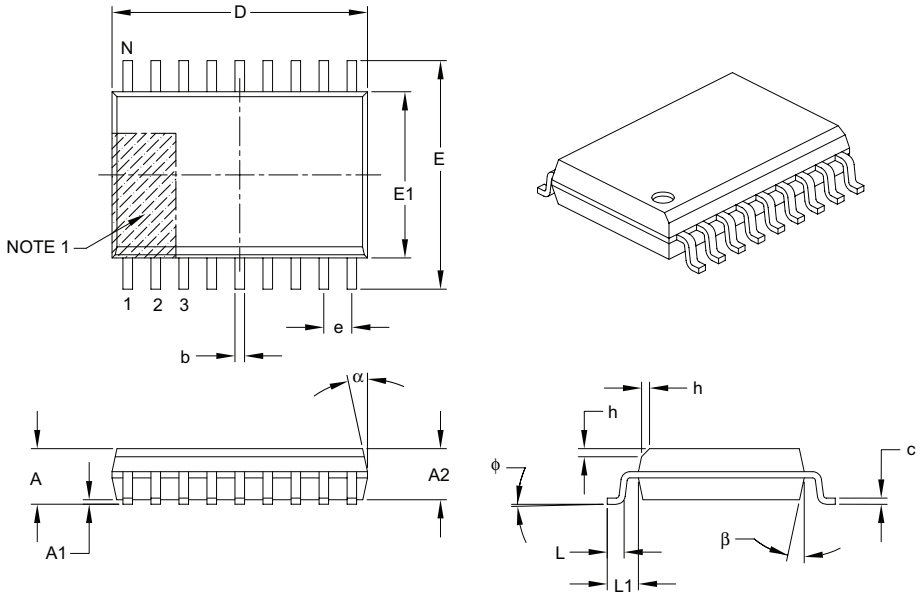
44-Lead TQFP





18-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	2.65
Molded Package Thickness	A2	2.05	–	–
Standoff §	A1	0.10	–	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		11.55 BSC	
Chamfer (optional)	h	0.25	–	0.75
Foot Length	L	0.40	–	1.27
Footprint	L1		1.40 REF	
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.20	–	0.33
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

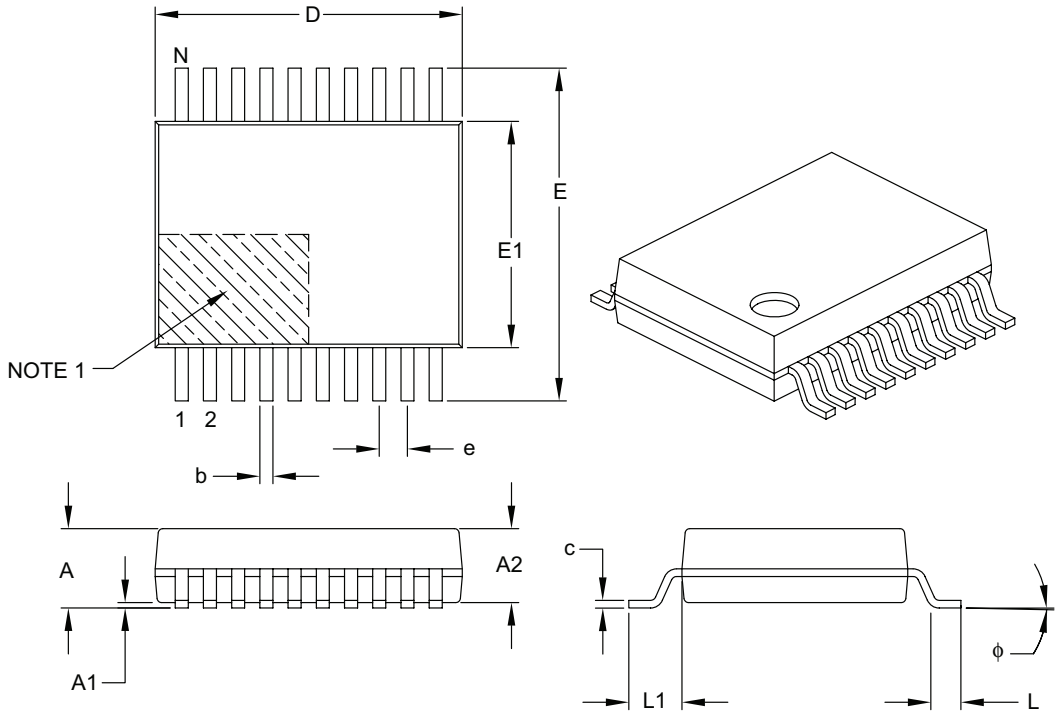
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-051B

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

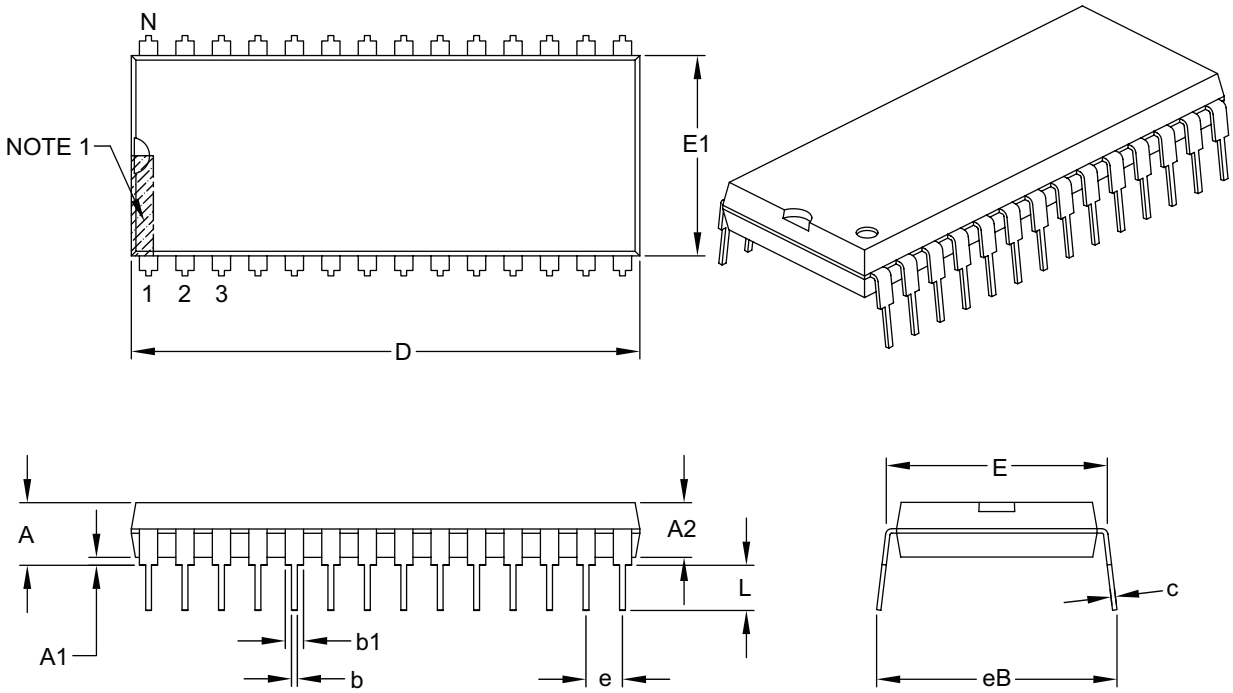
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

28-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.380	–	1.565
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.022
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-079B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision D (04/2007)

Changed PICmicro to PIC; Replaced Dev. Tool Section; Updated Package Marking Information and replaced Package Drawings (Rev. AP)

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